

AI

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. FL-AAS(flameless atomic absorption spectrometry) ICP-MS(inductively coupled plasma mass spectrometry)

TDS(thermal desorption spectroscopy)

가

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APIMS(atmospgeric pressure ionization mass spectroscopy)

가 . Si

XPS(X-ray photoelectron

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spectroscopy) FTIR(Fourier transform infrared spectroscopy)

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1. Total reflection X-ray fluorescence spectrometer (TXRF)

TXRF X (total reflection) - - 가



Fig. 1. Simplified design of total reflection X-ray fluorescence Spectrometer

C, O 가 TXRF가

가

TXRF X-

*X_P*フト 10nm

vaporization nm cathodic sputtering

2. Atomic force microscopy (AFM)

AFM (Probe Tip) Scanning , 가 . STM (Tunneling Current)가 , AFM

Scanning

. AFM

SFM(Scanning Force Microscopy)



STM . STM Constant Current Mode Constant Height Mode 가 가 . SPM AFM STM







Fig. 3. XPS



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4. Fourier transform infrared spectrometer (FT-IR)

FTIR Michelson interferometer (optical pathway) (interferogram) . , IR

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가

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(Time domain spectrum) INTER-FEROGRAM , 가 . ,

(, frequency domain spectrum) . Fourier transform(FT)

Fourier transform infrared spectrometer(FTIR)

FTIR

, / (signal to noise ratio) . FTIR

5. Auger electron spectroscopy (AES)

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Angstrom electron beam

Auger

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Figure 4. Schematic diagram of the Auger electron emission process



Charging Effect

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- : gold coating, silver paste

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- .
- .

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- (0.1%)
- Bulk